REMARKS

This paper responds to the Office Action dated June 30, 2005.

Claims 60, 66, 74, 88-90 are amended. Claims 60-62, 64-82, and 84-90 remain pending in this application.

§102 Rejection of the Claims

Claims 60, 61, 64-79 and 88-90 were rejected under 35 U.S.C. § 102(e) for anticipation by Reinberg (U.S. 6,432,793).

Applicant respectfully traverses.

Independent claim 60 is amended and recites, among other things, "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Applicant is unable to find in Reinberg "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 60 and its dependent claims.

Independent claim 66 is amended and recites, among other things, "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Applicant is unable to find in Reinberg "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 66 and its dependent claims.

Independent claim 74 is amended and recites, among other things, "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Applicant is unable to find in Reinberg "forming a metalization layer, the metalization layer including a first portion coupled to the diffusion barrier layer, and a second portion coupled to the substrate". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 74 and its dependent claims.

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Independent claim 88 is amended and recites, among other things, "forming a metallization layer, the metalization layer including a first portion coupled to the inhibiting layer, and a second portion coupled to the substrate, the metallization layer includes a metal material". Applicant is unable to find in Reinberg "forming a metallization layer, the metalization layer including a first portion coupled to the inhibiting layer, and a second portion coupled to the substrate, the metallization layer includes a metal material". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 88.

Independent claim 89 is amended and recites, among other things, "forming a metallization layer including a first portion having a barrier layer contacting the inhibiting layer, and a second portion coupled to the substrate, the barrier layer includes metal material". Applicant is unable to find in Reinberg "forming a metallization layer including a first portion having a barrier layer contacting the inhibiting layer, and a second portion coupled to the substrate, the barrier layer includes metal material". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 89.

Independent claim 90 is amended and recites, among other things, "forming a metallization layer over the inhibiting layer, the metallization layer including a first portion having a diffusion barrier layer contacting the inhibiting layer, and a second portion coupled to the substrate, wherein the diffusion barrier layer includes a metal material". Applicant is unable to find in Reinberg "forming a metallization layer over the inhibiting layer, the metallization layer including a first portion having a diffusion barrier layer contacting the inhibiting layer, and a second portion coupled to the substrate, wherein the diffusion barrier layer includes a metal material". Accordingly, Applicant requests reconsideration and withdrawal of the rejection, and allowance of claim 90.

Allowable Subject Matter

Applicant acknowledges allowance of claims 62, 80-82, and 84-87.

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Title: STRUCTURES AND METHODS FOR IMPROVED CAPACITOR CELLS IN INTEGRATED CIRCUITS

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance, and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney at (612) 373-6969 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By his Representatives,

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